

The 2nd World Conference on Intelligent and 3D Technologies (WCI3DT2023)

Shanghai, China May 26-28, 2023

CALL FOR PAPERS (CFP) || WCI3DT2023

The 2nd World Conference on Intelligent and 3D Technologies

May 26-28, 2023, Shanghai, China

Web: www.3dwcai.com

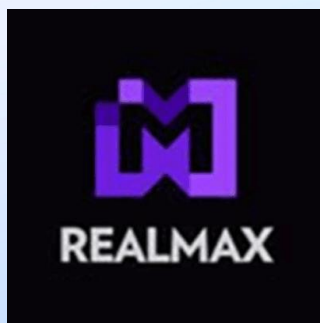
CONFERENCE OVERVIEW

The 2nd World Conference on Intelligent and 3D Technologies(WCI3DT2023) will be held from May 26-28, 2023 in Shanghai, China.

The WCI3DT aims to provide a forum that brings together researchers and academia as well as practitioners from industry to meet and exchange their ideas and recent research development work on all aspects of 3D Imaging Technologies and Artificial Intelligence, their applications and other related areas. The focus of the Conference is to establish an effective platform for institutions and industries to share ideas and to present the works of scientists, engineers, educators and students from all over the world. A key aspect of this Conference is the strong mixture of academia and industry.

This Conference brings the experts, practitioners, scientists and decision-makers from academia and industry together. Our aim is to foster a strong, lively and well-connected international research community. We welcome innovative ideas, concepts, services, techniques, research outputs and business practices.

ORGANIZERS



CO-ORGANIZERS



CALL FOR PAPERS

The topics of interest for submission include, but are not limited to:

Artificial Intelligence Methods and Technology

- Artificial Intelligence Algorithms
- Neural Networks
- Deep Machine Learning
- Computational Theories of Learning
- Pattern Recognition
- Computer Vision and Speech Understanding
- Visual Information Processing
- Probabilistic Reasoning
- Evolutionary Computation
- Fuzzy Systems
- Rough and Fuzzy Rough Set
- Reasoning and Evolution
- Data and Web Mining
- Data Visualization
- Biometrics
- Pervasive Computing and Ambient Intelligence
- Semantic Web Techniques and Technologies
- Soft Computing Theory

Artificial Intelligence Applications

- Artificial Intelligence Tools and Applications
- Heuristic and AI Planning Strategies and Tools
- Hybrid Intelligent Systems
- Intelligent Agent
- Information Retrieval
- Intelligent Control
- Intelligent Systems Architectures

- Intelligent and Knowledge based System
- Distributed AI
- Web Intelligence Applications & Search
- Soft Computing and Applications
- Software & Hardware Architectures
- Parallel Processing

Robotics Science and Engineering

- Robot Control
- Mobile Robotics
- Intelligent Pension Robots
- Mobile Sensor Networks
- Perception Systems
- Micro Robots and micro-manipulation
- Visual Serving
- Search, Rescue and Field Robotics
- Robot Sensing and Data Fusion
- Indoor Localization and Navigation
- Dexterous Manipulation
- Medical Robots and Bio-robotics
- Human Centered Systems
- Space and Underwater Robots
- Tele-robotics

Control Engineering

- Man-machine Interactions
- Nonlinear Systems and Control
- Discrete Event Systems
- Hybrid Systems
- Adaptive and Robust Control
- Data/Event Driven Modeling and Control
- Networked Control Systems
- Process Control
- Control of Biological Systems
- Cooperative Control
- Multi-agent Systems
- Optimal Control
- Fault Diagnosis
- Intelligent Transportation Systems
- Nano-scale Automation and Assembly
- Power System Control
- Cyber Physical Systems
- Factory Modeling and Simulation
- Production Planning, Scheduling and Control
- Intelligent Manufacturing
- Embedded System and Wireless Sensor Network

- Computational Intelligence in Automation

3D Image Technologies and Devices

- 3D Image Transformation
- 3D Tensor Image Representation
- N-D Image Processing
- 3D Deep Learning
- 3D Content Generation Technologies
- 3D Imaging Technology and Applications
- 3D Graphic Information Processing
- 3D Measurement and Standards
- VR Content Generation Technologies
- 3D Printing Technology
- Naked 3D Display
- Dynamic 3D Display
- Auxiliary 3D Display
- VR/AR/MR Device
- VR Camera Technology
- 3D Information Technology

IMPORTANT DATES

Final Submission Due: April. 30, 2023

Date of Conference: May 26-28, 2023

COMMITTEE

Honorary Chair:

Prof. Lakhmi C. Jain, Liverpool Hope University, UK / University of Technology Sydney, Australia

General Chairs:

Prof. Wenfeng Wang, International Academy of Visual Art and Engineering, London, UK

Prof. Dr. Srikanta Patnaik, I.I.M.T., Bhubaneswar, Odisha, India

Prof. Dr. Roumen Kountchev, Technical University of Sofia, Bulgaria

Prof. Xudong Jiang, Nanyang Technological University, Singapore

Organizing Chair:

Dr. Yonghang Tai, Yunnan Normal University, China

Dr. Shoulin Yin, Shenyang Normal University, China

Dr. Prof. Hang Li, Shenyang Normal University, China

International Advisory Chair:

Dr. Roumiana Kountcheva, Technical University of Sofia, Bulgaria

Technical Program Committee:

Prof. Wenfeng Wang, IIMTcair, China

Prof. Yuhong Gu, Shihezi Medical School, China

Prof. Feng Liu, Nanjing University of Finance and Economics, China

Prof. Ying Huang, IIMTcair, China

Prof. Xiaoqiang Li, IIMTcair, China

Prof. Qi Xiong, Hunan University of Arts and Science, China
Prof. Antonios Andreatos, Hellenic Air Force Academy, Greece
Prof. Vladicescu Popentiu, Florin, City University, UK
Prof. Guangzhi Qu, Oakland University, USA
Prof. V.S.S. Yadavalli, University of Pretoria, South Africa
Prof. Bruno Apolloni, Università degli Studi di Milano, Italy
Prof. Harry Bouwman, Delft University of Technology, Netherlands
Prof. Shyi-Ming Chen, National Taiwan University of Science and Technology, Taiwan
Prof. Yahaya Coulibaly, University Technology Malaysia, Malaysia
Prof. Ing Kong, RMIT University, Australia
Prof. Gerald Midgley, Centre for Systems Studies, Business School, University of Hull, UK
Prof. Khubaib Ahmed, Hamdard University, Pakistan
Prof. Dorian Cojocar, University of Craiova, Romania
Prof. Moustafa Mohammed Eissa, Faculty of Engineering-Helwan University, Egypt
Prof. Dr. Md. Shamim Anower, Rajshahi University of Engineering & Technology, Bangladesh
Dr. Fernando Boronat Seguí, Universitat Politècnica de Valencia, Spain
Dr. Alexandros Fragkiadakis, Institute of Computer Science (FORTH-ICS), Greece
Dr. Cristina Alcaraz, University of Malaga, Spain
Dr. Mohamed Atef, Assiut University, Egypt
Dr. Weilin Wang, University of Georgia, USA
Dr. Bensafi Abd-Ei-Hamid, World Islamic Sciences and Education University, Jordan
Dr. Yudi Gondokaryono, Institute of Teknologi Bandung, Indonesia
Dr. Hadi Arabshahi, Ferdowsi University of Mashhad, Iran
Dr. Qian Lv, Western Digital, USA
Dr. Alojz Poredo, University of Ljubljana, Slovenia
Dr. Mohamed F. El-Santawy, Cairo University, Egypt
Dr. Tongpin Liu, University of Massachusetts Amherst, USA
Dr. Seema Verma, Banasthali University, India
Dr. Imran Memon, Zhejiang University, Pakistan
Dr. Hao Fu, Facebook Inc., USA
Dr. Maryam Zahid, Capital University of Science and Technology, Pakistan
Dr. Corneliu Doroftei, Alexandru Ioan Cuza University of Iasi, Romania

PUBLICATION OF CONFERENCE PROCEEDINGS:

All accepted papers of WCI3DT2023 will be published in Smart Innovation, Systems and Technologies (ISSN: 2190-3018) by Springer. Smart Innovation, Systems and Technologies (ISSN: 2190-3018) of this series will be Indexed by EI Compendex, SCOPUS, INSPEC and Springerlink .



PAPER SUBMISSION GUIDELINES:

- WCI3DT 2023 accepts original and unpublished papers.
- All submitted papers must be written in English.
- Each paper should be at least 8 pages or longer, including tables, graphs, charts & references.
- Article repetition rate cannot be higher than 18%, otherwise it will be rejected directly.
- All papers submitted will be subjected to thorough peer-review based on originality, technical quality, and presentation.

CONTACT US:

Conference Secretary (Miss. Cao)

QQ: 2721004616

Phone: +86-15581016632

Email: WCI3DT@163.com



The 2nd World Conference on Intelligent and 3D Technologies WCI3DT2023

Shanghai, China

May 26-28, 2023